

II. AMENDMENTS TO THE SPECIFICATIONS:

Please replace paragraph 27 of the specification with the following amended paragraph:

[0027] FIGS. 8-16 show continuing steps of well known SiGe technology that ultimately result in the final high performance NPN and PNP transistors. These steps are outlined in ~~U.S. Patent No. 5,111,271~~ Comfort et al. (U.S. Patent No. 5,117,271), hereby incorporated by reference. It should be recognized that these steps may vary somewhat as the integration scheme is adapted to different applications. FIG. 8 shows a step in which an oxide layer 52 is grown over the entire wafer, followed by deposition of a nitride layer 54 and finally a polysilicon layer 56.